COMPONENT MATRIX

Limitless versatility

INFOTECH COMPONENT MATRIX

Configuration according to your requirements:
The Infotech Component Matrix offers a wide range of machine components which are capable of being combined depending on to the customer`s requirements. A platform can be integrated in a production cell or configured as Desktop system.
Over 1000 components out of the Infotech Component Matrix can be combined, fulfilling all feasible needs.
Each machine is designed, optimized and project specifically built according to your requirements.

From the compact Desktop machine to the inline-capable fully automatic Production Cell

Process automation for applications such as dispensing, assembling, sorting, testing, handling and feeding

100% of development and 95% of production located in Switzerland

PRODUCTION CELLS

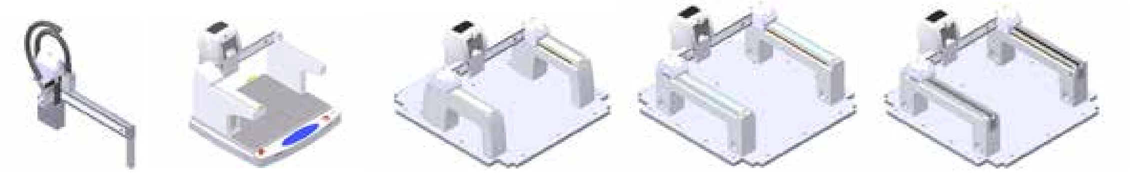
IC-900

IC-1200

IC-1800

IC-2000

PLATFORMS

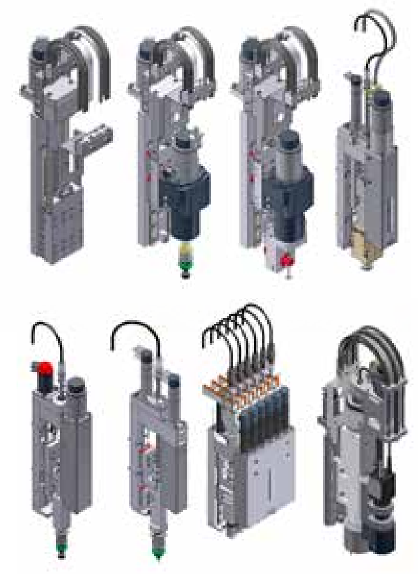


	IP - 100	IP - 500 DESKTOP	IP - 520	IP - 620	IP - 720
TRAVEL RANGE X in mm	93, 148	400	210, 270, 340, 400, 540	210, 270, 340, 400, 540	210, 270, 340, 400, 540
TRAVEL RANGE Y in mm	440, 550, 680	400	400	400, 540, 630, 730	540, 650, 730
REPEATABILITY	±0.005 mm @ 3σ	±0.005 mm @ 3σ	±0.004 mm @ 3σ	±0.004 mm @ 3σ	±0.004 mm @ 3σ
PROCESS ACCURACY	±0.010 mm @ 3σ	±0.010 mm @ 3σ	±0.009 mm @ 3σ	±0.010 mm @ 3σ	±0.010 mm @ 3σ
MACHINE CAPABILITY cm /cmk	1.66/1.33	1.66/1.33	1.66/1.33	1.66/1.33	1.66/1.33

ASSEMBLING

The assembly modules from the Infotech Component Matrix can be combined with functions in the areas of dispensing, joining, handling, mounting, testing and many more. Assembly tasks are performed precisely and reliably and are combinable with further process steps.

- Universal Z-axes with various widths
- Precision assembly head
- Assembly heads with various widths
- Up to 6 assembly heads
- Heated bond head
- Ultrasonic bond head
- Automatic changeable nozzle interface
- Nozzle change stations
- Standard SMD and die bonding nozzles
- Special nozzles spring loaded and stiff
- Special gripper
- Force controlled assembly
- Automatic and eccentric nozzle offset calibration
- Nozzle ID reading (traceability)



DISPENSING

- Dots, lines, geometric patterns 2D / 3D
- X-, Y-, Z- and valve synchronized with continuous motion path control
- Time / pressure dispensing units
- Archimedes screw dispensing units
- Precision micro screw dispensing units
- Electro-pneumatic and piezoelectric jet dispensing units
- Piston dispensing units for 1C- and 2C- adhesive with dynamic mixer
- Syringe and needle heaters, syringe coolers
- Automatic compensation of viscosity variations
- Automatic Z-needle length calibrations
- Automatic X- and Y-offset calibrations
- Purge, weight scale, and calibration stations
- Dispensing calibration and cleaning tape units
- Dispensing needle cleaning stations

FEEDING

Infotech develops and produces loading and unloading systems for all types of feeding formats. If a standard feeding system isn`t currently available we offer customer specific solutions. For instance, a workpiece carrier can be preheated on its way to the process station or after a gluing process be cured by UV-light.

- SMD tape feeder 8 ... 72 mm
- 2 ... 22 slot feeder bank
- Preform feeder PF2-14, PF12-26 and PF22-36
- Preform stack feeder PS32-66
- Stack tray feeder unit for 2" x 2", 4" x 4" and Jedec
- Stack tray feeder for non standard dimensions
- Asycube 50, 80, 240, 530
- Vibration and bowl feeder units
- Die and FlipChip eject unit for 4" ... 12" wafer
- Wafer change unit for 6" ... 12" wafer frames
- Transport systems for substrates, boards, work piece carriers, Auer boats, lead frames, etc.
- Heatable transport sections
- Loading and unloading modules
- Transfer shuttle system

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